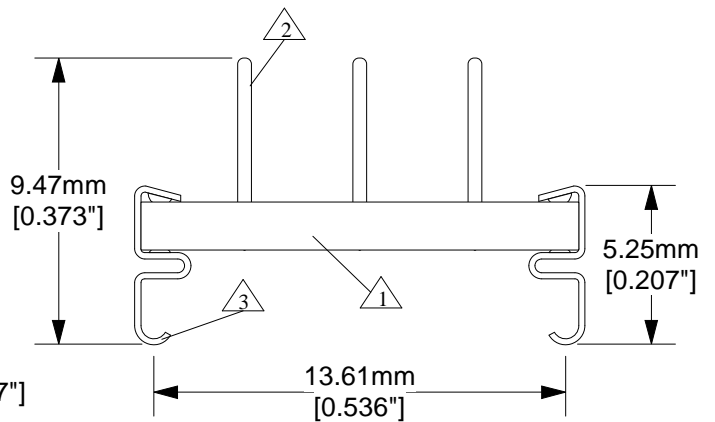
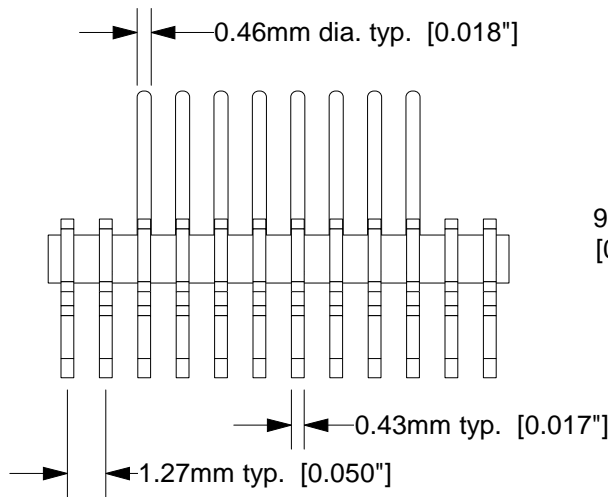
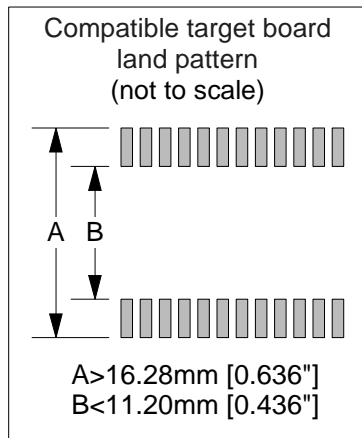


Top View



End View

Side View




- ① Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. SnPb plating.
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).
- ③ Leads: material- BeCu Alloy 194; plating- 60/40 SnPb 3.80-10.16 μ m [150-400 μ].

Description: SO Surface Mount Emulator Foot

24 position (0.05" pitch) J-leaded surface mountable emulator foot, with mini grid array (MGA) pin interface.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise.

	SF-SO24F-J-02 Drawing	Status: Released	Scale: 3:1	Rev: D
	© 1997 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: T. JOHNSON		Date: 3/25/97
		File: SF-SO24F-J-02 Dwg		Modified: 4/27/00